



LNP™ STAT-LOY™ Compound 63000CTU

Asia Pacific: COMMERCIAL

A permanent antistatic PC-Alloy compound that features transparency, UV cut, and superior cleanliness for advanced semiconductor packaging applications

TYPICAL PROPERTIES ¹	TYPICAL VALUE	Unit	Standard
MECHANICAL			
Tensile Stress, brk, Type I, 5 mm/min	360	kgf/cm ²	ASTM D 638
Tensile Strain, break	200	%	ASTM D 638
Tensile Modulus, 50 mm/min	11800	kgf/cm ²	ASTM D 638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	540	kgf/cm ²	ASTM D 790
Flexural Modulus	12300	kgf/cm ²	ASTM D 790
IMPACT			
Izod Impact, notched, 23°C	50	cm-kgf/cm	ASTM D 256
Charpy Impact, notched, 23°C	69	kJ/m ²	ISO 179/2C
THERMAL			
HDT, 0.45 MPa, 6.4 mm, unannealed	83	°C	ASTM D 648
HDT, 1.82 MPa, 6.4 mm, unannealed	74	°C	ASTM D 648
PHYSICAL			
Density	1.16	g/cm ³	ASTM D 792
Mold Shrinkage, flow (5)	0.6	%	SABIC Method
Mold Shrinkage, xflow (5)	0.6	%	SABIC Method
Melt Flow Rate, 260°C/2.16 kgf	19	g/10 min	ASTM D 1238
Moisture Absorption (23°C / 50% RH)	0.7	%	ISO 62
OPTICAL			
Light Transmission at 3.0 mm	35	%	SABIC Method
Haze, 2.54 mm	10	%	ASTM D 1003
ELECTRICAL			
Volume Resistivity	1.E+11 - 5.E+12	Ohm-cm	ASTM D 257
Surface Resistivity	1.E+11 - 5.E+12	Ohm	ASTM D 257
Static Decay, 5000V to <50V	2	< seconds	FTMS101B
Volume Resistivity	0.E+00	Ohm-cm	IEC 60093



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PROCESSING PARAMETERS	TYPICAL VALUE	Unit
Injection Molding		
Drying Temperature	90 - 95	°C
Drying Time	6 - 8	hrs
Melt Temperature	230 - 250	°C
Nozzle Temperature	230 - 250	°C
Front - Zone 3 Temperature	230 - 250	°C
Middle - Zone 2 Temperature	225 - 240	°C
Rear - Zone 1 Temperature	220 - 230	°C
Mold Temperature	40 - 50	°C